

Title (en)

A METHOD AND DEVICE FOR REMOVING A SURFACE MOUNTED COMPONENT FROM A CIRCUIT BOARD

Title (de)

VERFAHREN UND VORRICHTUNG ZUR ENTFERNUNG EINER OBERFLÄCHENMONTIERTEN KOMPONENTE VON EINER LEITERPLATTE

Title (fr)

PROCEDE ET DISPOSITIF PERMETTANT D'ENLEVER UN COMPOSANT MONTE EN SURFACE D'UNE CARTE IMPRIMEE

Publication

**EP 0764394 A1 19970326 (EN)**

Application

**EP 95902374 A 19941124**

Priority

- SE 9401124 W 19941124
- SE 9303909 A 19931125

Abstract (en)

[origin: WO9515073A1] A method and a device for removing a surface mounted component (11) from a circuit board (10), the component being attached by means of an adhesive joint. According to the method the component and the adhesive joint are subjected to a thermal shock by being cooled down and are imparted with such internal mechanical stresses that the component is loosened. The device comprises means (16, 17, 18) for supplying cooling medium to the component (11), shielding means (15) for shielding the component (11) from other components (12) and control means (19) for controlling the supply of the cooling medium and for positioning the shielding means (15) in relation to the component (11).

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